Amongst multiple emerging non-volatile memory (NVM) technologies, spin transfer torque magneto resistive RAM (STT-MRAM) has shown significant potential and market growth driven by low latency storage applications. In 2018 the MRAM market recorded revenue of $44 million. It is estimated that the compound annual growth rate for the MRAM market will be 85% between 2018 and 2024.

Magnetoelectronic memories have been employed in numerous information devices because of their non-volatile characteristics, high speed and low power consumption. Their high endurance characteristics have made STT MRAM a good competitor in the memory industry. It promises to pick up significant market share in the next few years.

Everspin’s STT MRAM component has a compact structure integrating numerous layers that include ferromagnetic and antiferromagnetic material, forming a magnetic tunnel junction. Different resistive states created in the MRAM cell allow read and write functions. A dielectric layer is coupled between two magnetic materials. A complex fabrication method is used to deposit and pattern the thin layers that form the STT MRAM cell.

Everspin Technologies leads the STT-MRAM market. Its 256Mb STT MRAM memory uses a 40 nm lithographic technology node process. The memory is manufactured along with CMOS transistors.

System Plus Consulting presents a deep analysis of Everspin’s EMD3256M STT MRAM. The report includes an analysis of the package and the dies, the MRAM cell, focusing on the layered material that makes up the MRAM cell. It also features a cost analysis and price estimation of the component. This cost analysis integrates the manufacture of CMOS transistors and MRAM cells. The manufacturing process steps are detailed, as is the supply chain. The manufacturing cost results are used to determine the cost per Mb for Everspin’s STT MRAM.
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AUTHORS

Belinda Dube is working for System Plus Consulting as Analyst in Semiconductor Memories and Integrated Circuits. She holds a Masters degree in Nano Science and Nanotechnologies from Ecole Central Lyon and INSA Lyon.

Nicolas Radufe is in charge of physical analysis at System Plus Consulting. He has a deep knowledge in chemical and physical analyses. He previously worked in microelectronics R&D for CEA/LETI in Grenoble and for STMicroelectronics in Crolles.

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Reverse Costing® is the process of disassembling a device (or a system) in order to identify its technology and calculate its manufacturing cost, using in-house models and tools.

CONTACTS

Headquarters
22, bd Benoni Goullin
Nantes Biotech
44200 Nantes
France
+33 2 40 18 09 16
sales@systemplus.fr

Europe Sales Office
Lizzie LEVENEZ
Frankfurt am Main
Germany
+49 151 23 54 41 82
llevenez@systemplus.fr

America Sales Office
Steven LAFFERIERE
Western USA & Canada
+1 310-600-8267
lafferiere@yole.fr

Chris YOUUMAN
Eastern USA & Canada
+1 919-607-9839
chris.youman@yole.fr

Asia Sales Office
Takashi ONOZAWA
Japan & Rest of Asia
+81 80 4371 4887
onozawa@yole.fr

Mavis WANG
Greater China
TW +886 979 336 809
CN +8613661566824
wang@yole.fr

Peter OK
Korea
+82 10 4089 0233
peter.ok@yole.fr

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